



DESCRIPTION

$V_{DS} = 100V$
 $V_{GS} = \pm 20V$
 $ID(A) = 120A$
 $R_{DS(ON)} = 4.8m\Omega$ (max.) @ $V_{GS}=10V$

FEATURES

- 100% UIS + R_g Tested
- Reliable and Rugged
- Available in TO-220 package.

AM0292 is available in TO-220 package.

ORDERING INFORMATION

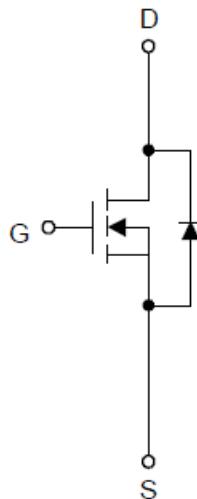
Package Type	Part Number	
TO-220 SPQ: 50pcs/Tube	T3	AM0292T3U
		AM0292T3VU
Note	V: Halogen free Package U: Tube	

AiT provides all RoHS products

APPLICATION

- High Efficiency Synchronous Rectification in SMPS.
- Uninterruptible Power Supply.
- Hard Switched and High Frequency Circuits.

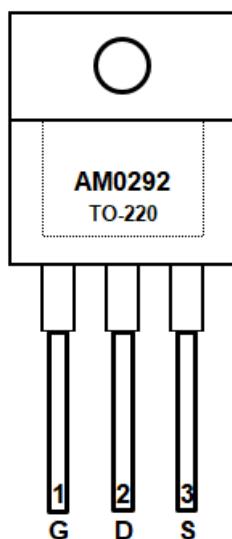
N CHANNEL MOSFET



N-Channel MOSFET



PIN DESCRIPTION



Top View

Pin #	Symbol	Function
1	G	Gate
2	D	Drain
3	S	Source



ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted

V_{DSS} , Drain-Source Voltage	100V	
V_{GSS} , Gate-Source Voltage	$\pm 20\text{V}$	
T_J , Maximum Junction Temperature	150°C	
T_{STG} , Storage Temperature Range	$-55^\circ\text{C} \sim +150^\circ\text{C}$	
I_S , Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	70A
I_D , Continuous Drain Current	$T_c=25^\circ\text{C}$	120A ^{NOTE1}
	$T_c=100^\circ\text{C}$	86A
I_{DM}^{NOTE2} , Pulsed Drain Current	$T_c=25^\circ\text{C}$	400A
P_D , Maximum Power Dissipation	$T_c=25^\circ\text{C}$	192W
	$T_c=100^\circ\text{C}$	76W
$R_{\theta JC}$, Thermal Resistance-Junction to Case	$0.65^\circ\text{C}/\text{W}$	
I_D , Continuous Drain Current	$T_A=25^\circ\text{C}$	14.0A
	$T_A=70^\circ\text{C}$	11.2A
P_D , Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2.0W
	$T_A=70^\circ\text{C}$	1.28W
$R_{\theta JA}$, Thermal Resistance-Junction to Ambient	$62.5^\circ\text{C}/\text{W}$	
I_{AS}^{NOTE3} , Avalanche Current, Single pulse	$L=0.5\text{mH}$	42A
E_{AS}^{NOTE3} , Avalanche Energy, Single pulse	$L=0.5\text{mH}$	441mJ

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Calculated continuous current based on maximum allowable junction temperature. Bonding wire limitation current is 120A

NOTE2: Pulse width limited by maximum junction temperature.

NOTE3: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^\circ\text{C}$).



ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless otherwise noted

Parameter	Symbol	Conditions	Min	Typ.	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _{DS} =250μA	2	3	4	V
Gate Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Drain-Source On-state Resistance	R _{DS(ON)} NOTE4	V _{GS} =10V, I _{DS} =40A	-	4.0	4.8	mΩ
Diode Characteristics						
Diode Forward Voltage	V _{SD} NOTE4	I _{SD} =40A, V _{GS} =0V	-	0.8	1.3	V
Reverse Recovery Time	t _{rr}	I _{SD} =40A, dI _{SD} /dt=100A/μs	-	65	-	ns
Reverse Recovery Charge	Q _{rr}		-	135	-	nC
Dynamic Characteristics NOTE5						
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	20	-	Ω
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =30V, Frequency=1.0MHz	-	4450	5790	pF
Output Capacitance	C _{oss}		-	1420	-	
Reverse Transfer Capacitance	C _{rss}		-	50	-	
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, R _L =30Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	20	36	ns
Turn-on Rise Time	t _r		-	16	29	
Turn-off Delay Time	t _{d(off)}		-	74	134	
Turn-off Fall Time	t _f		-	118	213	
Gate Charge Characteristics NOTE5						
Total Gate Charge	Q _g	V _{DS} =50V, V _{GS} =10V, I _{DS} =40A	-	77	108	nC
Gate-Source Charge	Q _{gs}		-	20	-	
Gate-Drain Charge	Q _{gd}		-	18	-	

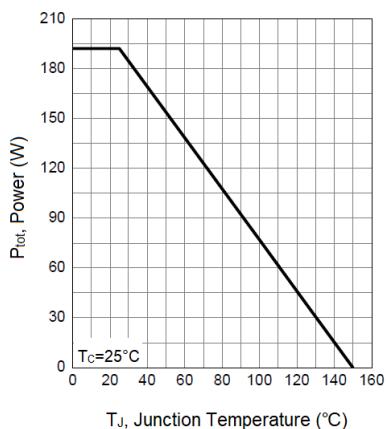
NOTE4: Pulse test; pulse width≤300μs, duty cycle≤2%.

NOTE5: Guaranteed by design, not subject to production testing.

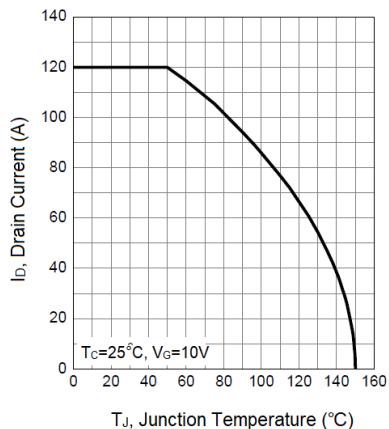


TYPICAL CHARACTERISTICS

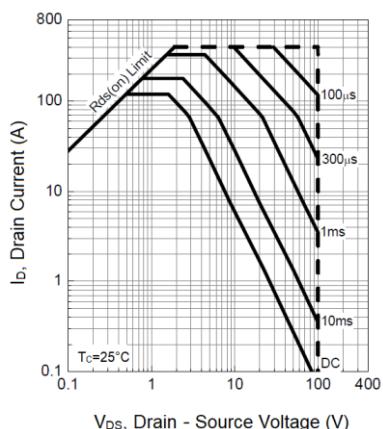
1. Power Dissipation



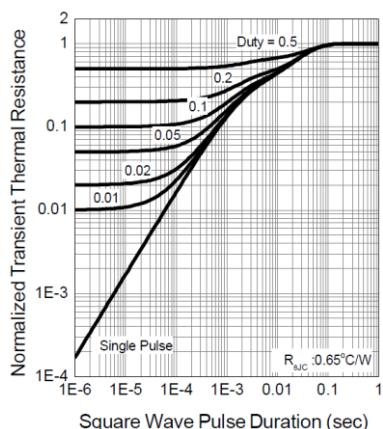
2. Drain Current



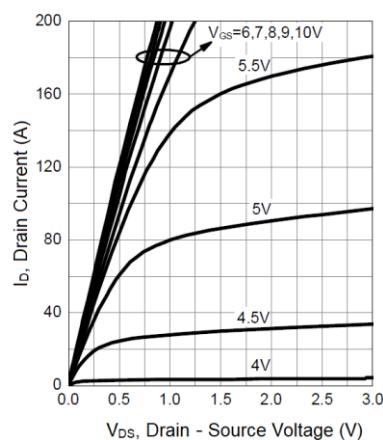
3. Safe Operation Area



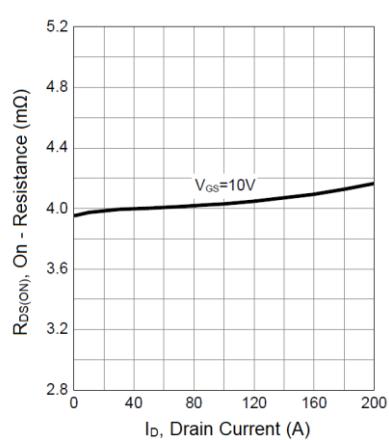
4. Thermal Transient Impedance



5. Output Characteristics

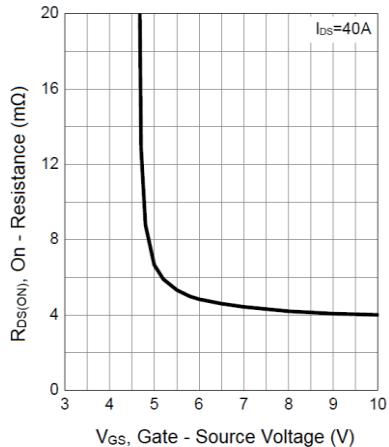


6. Drain-Source On Resistance

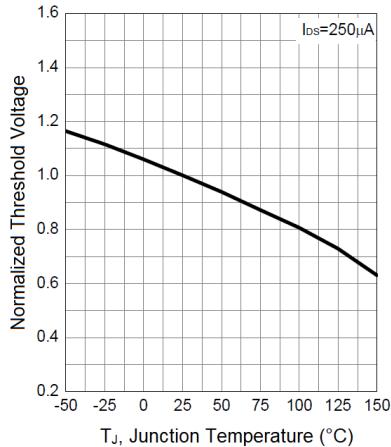




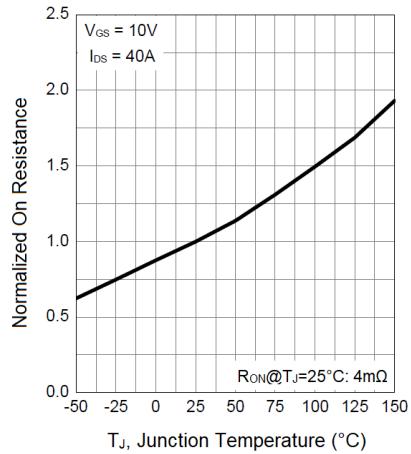
7. Gate-Source On Resistance



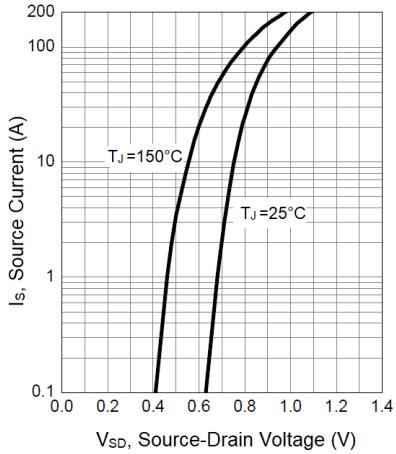
8. Gate Threshold Voltage



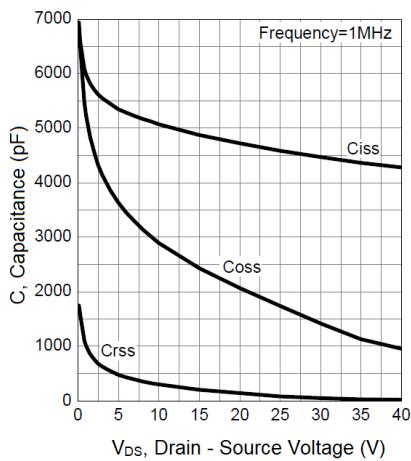
9. Drain-Source On Resistance



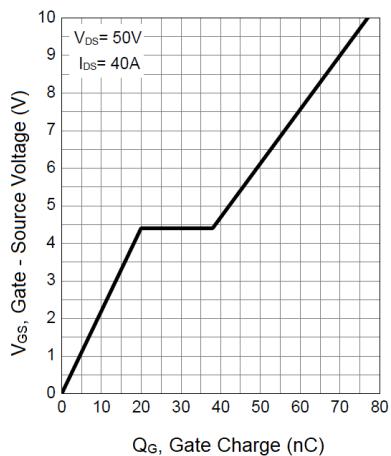
10. Source-Drain Diode Forward



11. Capacitance

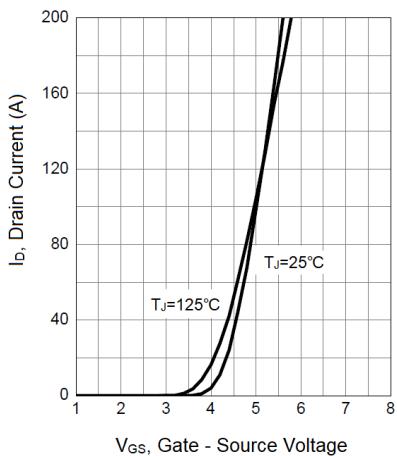


12. Gate Charge

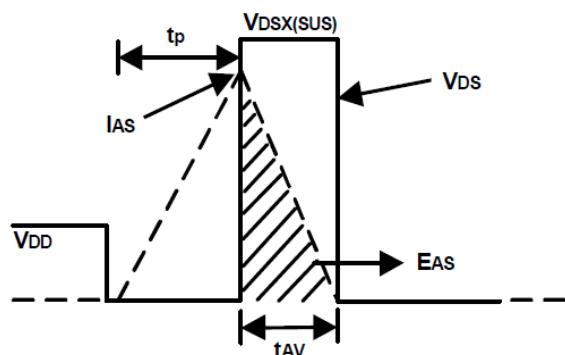
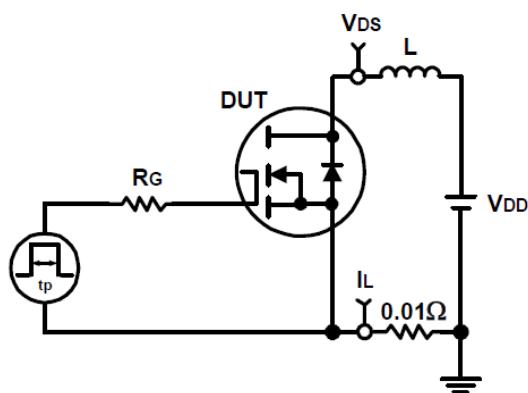




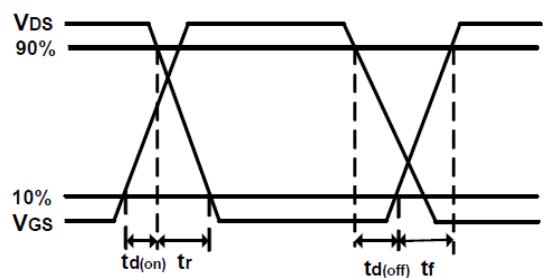
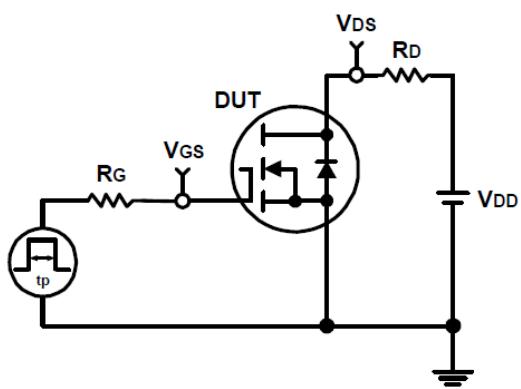
13. Transfer Characteristics



Avalanche Test Circuit and Waveforms



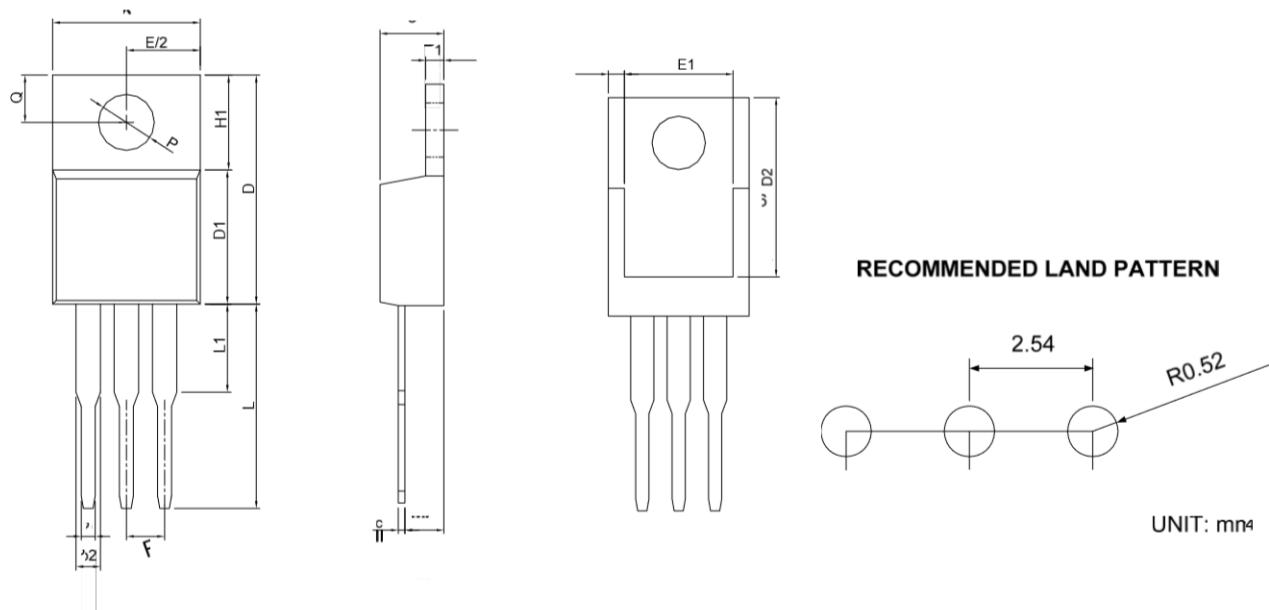
Switching Time Test Circuit and Waveforms





PACKAGE INFORMATION

Dimension in TO-220 (Unit: mm)



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.30	0.330	0.366
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135



IMPORTANT NOTICE

AiT Semiconductor Inc. (AiT) reserves the right to make changes to any its product, specifications, to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

AiT Semiconductor Inc.'s integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life support applications, devices or systems or other critical applications. Use of AiT products in such applications is understood to be fully at the risk of the customer. As used herein may involve potential risks of death, personal injury, or severe property, or environmental damage. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.

AiT Semiconductor Inc. assumes no liability to customer product design or application support. AiT warrants the performance of its products of the specifications applicable at the time of sale.